



A generational change in vibration sensing and motion tracking

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Agenda

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- 2 ISM330BX: the new smart industrial IMU
- 3 Q&A
- 4 Create your application with the ISM330BX ecosystem
- 5 Conclusions and takeaways
- 6 Q&A



Sensor requirements in industrial applications



Enabling leadership in Industry 5.0 through MEMS

Industry 4.0

Motion, vibration, Angle Measurement



Motion sensors Inclinometers

Temperature monitoring & calibration



Temperature sensors

Pressure monitoring



Pressure sensors

Humidity monitoring



Humidity sensors

Acoustic monitoring



MEMS microphones

Industry 5.0

Advanced interface



Artificial intelligence in the edge



Automation



Visual aid Laser beam scanning



Infrared sensor



Human centric

Helping individuals while working

Resilient

Based on versatile technology

Sustainable

Conceived to optimize processes



Focus applications domains

Condition monitoring Predictive maintenance





Industrial automation

Smart installations

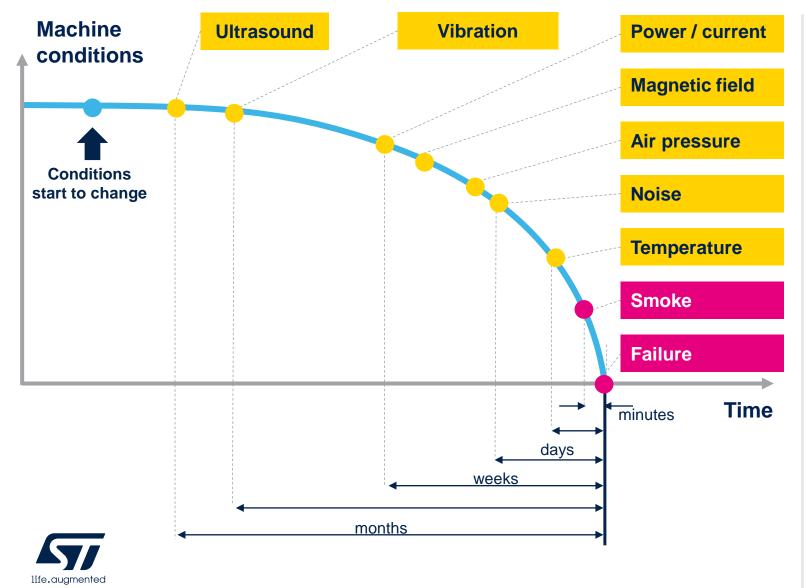


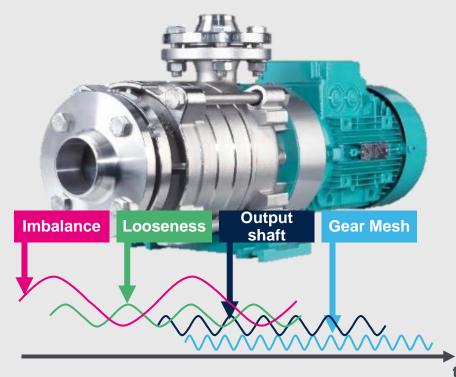


Asset tracking



Vibration sensors – Condition monitoring





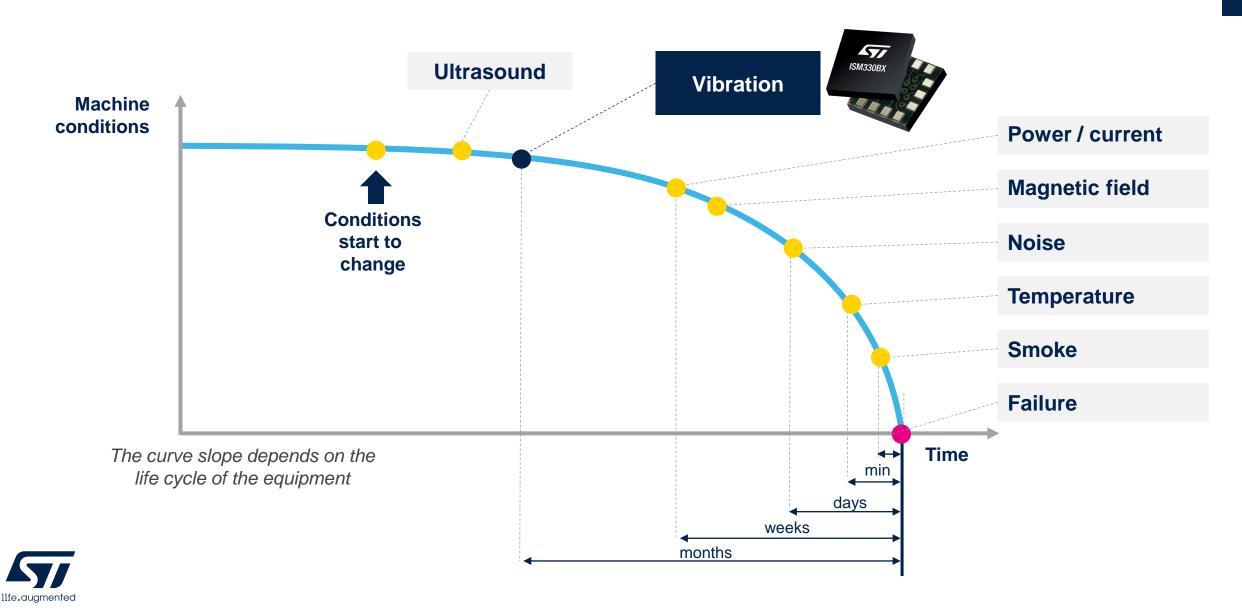
Mechanical vibration

- Displacement
- Speed
- Acceleration
- Angular speed
- Torque
- Acoustic noise

ISM330BX: the new smart industrial IMU



ISM330BX for condition monitoring





An intelligent & versatile IMU that does all by itself

Condition monitoring



Unique 3-axis
accelerometer with low
noise and wide bandwidth

Robotics



3D orientation tracking with sensor fusion low power (SFLP) + vibration sensing

Safety helmets



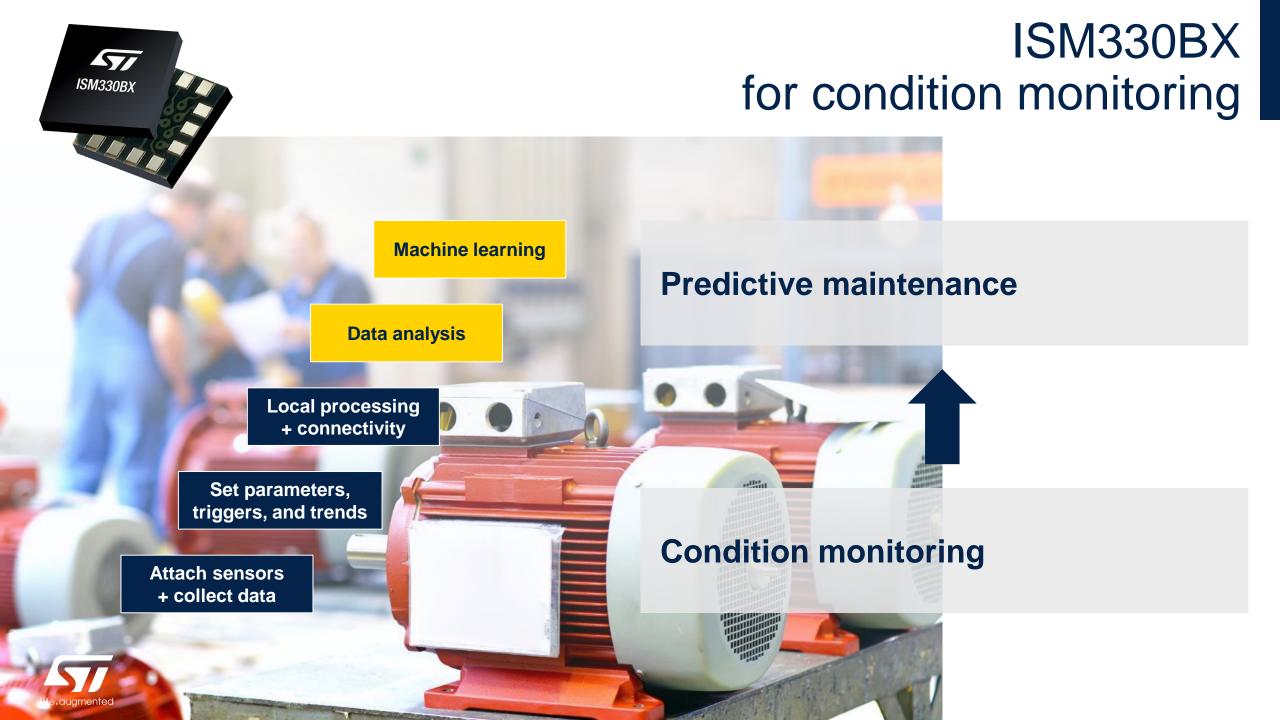
Proper helmet wearing, 3D orientation, shock events, free fall, man down

Appliances

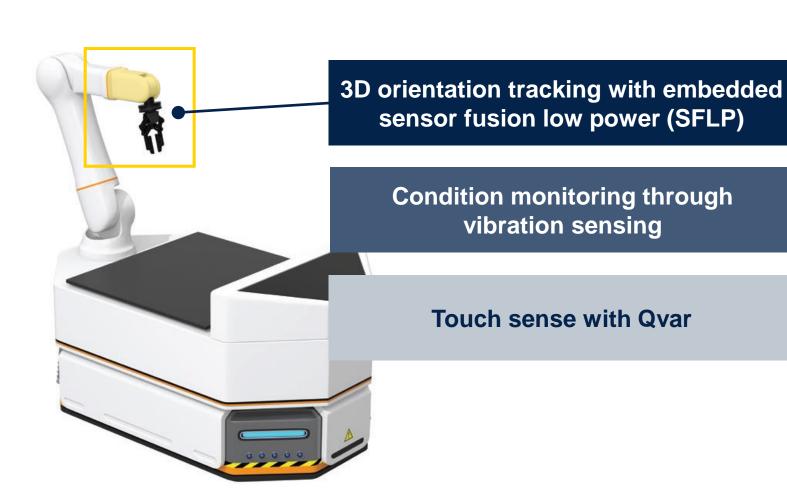


Vibration measurements and compensation, water leak detection, anomaly detection, tilt measurement





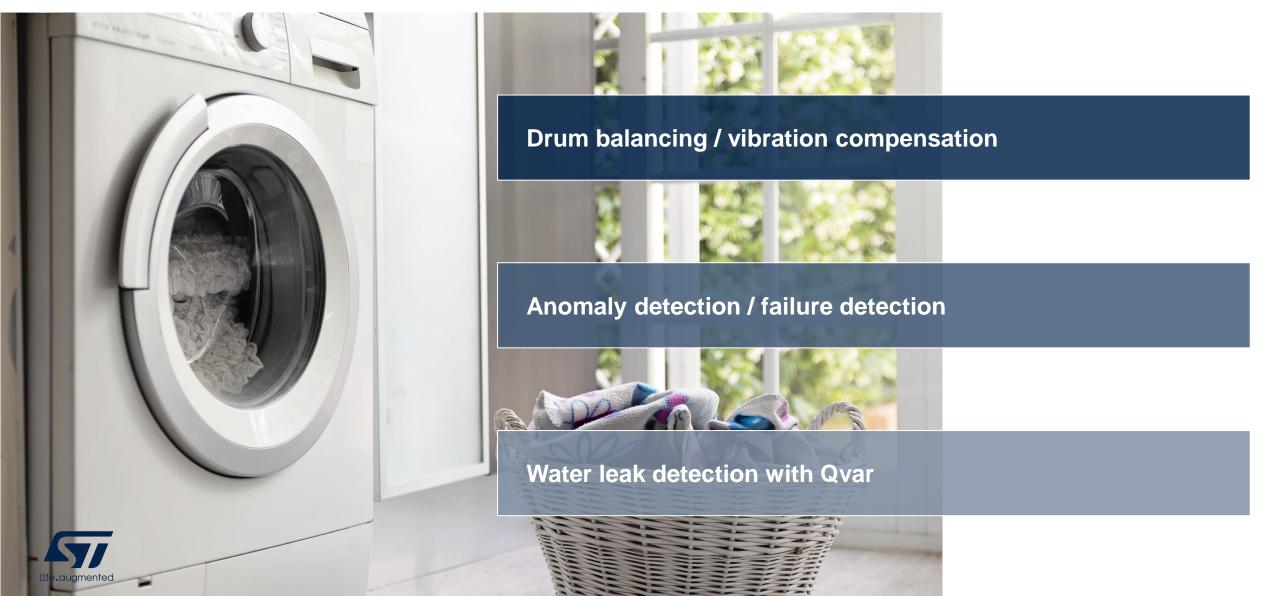
ISM330BX for robots The self-sufficient IMU!







ISM330BX for appliances you just need it!





ISM330BX

3rd generation 6-axis IMU with a wide bandwidth, low-noise 3-axis accelerometer







Multiple interfaces: SPI, I³C v1.1, TDM (for accelerometer only)

FS: Gyroscope 4000 dps, accelerometer 8 g

Intelligent sensor: MLC & FSM 2.0, ASC, sensor fusion low power (SFLP)

Embedded FIFO: 1.5 Kbyte (4.5 Kbyte with compression)

Accelerometer: up to 2 kHz bandwidth on 3 axis with flat frequency response

Low noise accelerometer: 70 μ g/ \sqrt{Hz} SPI - 30 μ g/ \sqrt{Hz} TDM

Low noise gyroscope: $4.5 \text{ mdps}/\sqrt{\text{Hz}}$

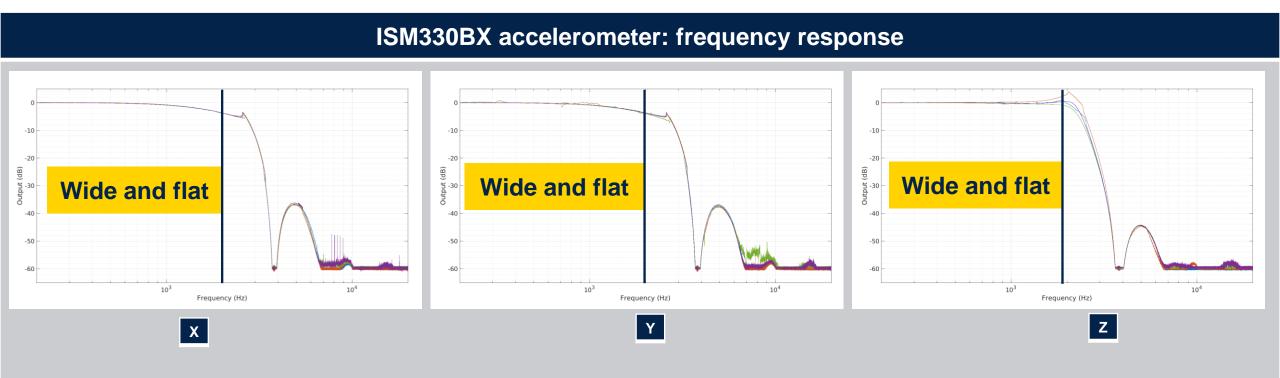
Low power consumption: 0.19 mA axel HP; 0.6 mA combo HP

Package: LGA 2.5 x 3 x 0.71 14L





ISM330BX offers a unique accelerometer Wide, flat, repeatable frequency response





Perfect to fulfill ISO10816 vibration severity standards

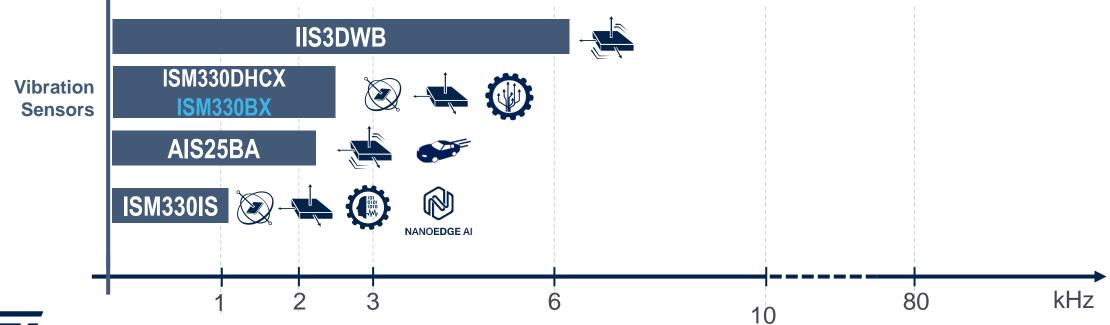
Vibration sensing for condition monitoring ST Offer













Comparing ISM330BX with other IMUs in the same family

	Bandwidth [kHz]	In-sensor Al	Sensor fusion low power	Embedded Qvar (electrostatic sensor)	Package size [mm]
ISM330BX	2	MLC and FSM	Yes	Yes	2.5 x 3.0 x 0.71 LGA-14L
IIS3DWB	6	-	-	No	2.5 x 3.0 x 0.86 LGA-14L
ISM330DHCX	2	MLC and FSM	-	No	2.5 x 3.0 x 0.86 LGA-14L
AIS25BA	2	-	-	No	2.5 x 3.0 x 0.86 LGA-14L
ISM330IS	1	ISPU	Yes (with library)	No	2.5 x 3.0 x 0.86 LGA-14L



ISM330BX is part of longevity program

10 years longevity commitment



ST focuses on markets requiring long life cycles

Protecting the investments of our customers that need state-of-the-art sensors but have long development, certification or field life cycles

10-year longevity from product introduction date

Design and manufacturing for higher robustness

Calibration & testing for higher accuracy & quality

Higher endurance to shock and vibration

Industrial temperature range

ISM330RX



ST's longevity program

ISM330BX moves the intelligence at the edge

MCU computing

Sensor + MCU

Intelligence in the MCU



MCU standalone or hosted in the sensor package

Standard

MCU runs the algorithms

Runs any kind of software

provided it matches the MCU specs

In-sensor AI computing

Sensor with MLC / FSM

Machine Learning Core Finite State Machine



MLC: reconfigurable processing unit integrated in the sensor ASIC

Optimized

Reconfigured through register setting

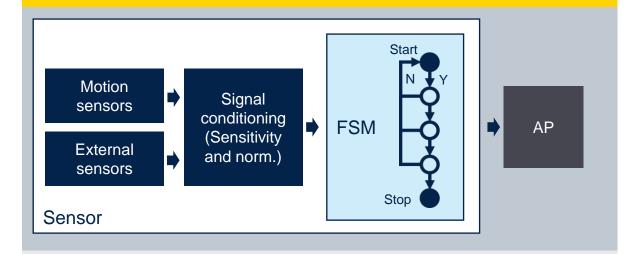
Constrained

Runs the same model / mapping (MLC, FSM)



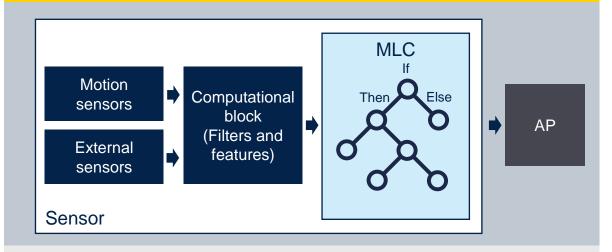
Edge processing with MLC and FSM

Finite state machine



- FSM is composed of a finite number of user-defined states and transitions between them
- FSM can be in just one of the states and move to another one only if the transition condition is met
- Each state can be composed of command or a next/reset condition

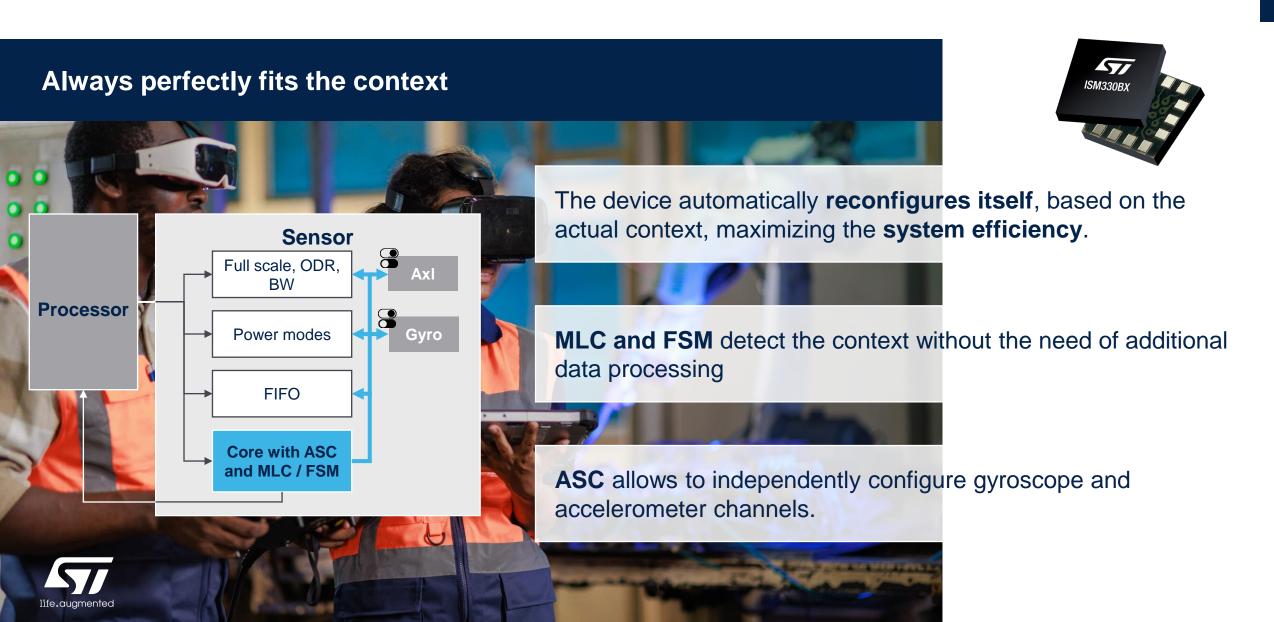
Machine learning core



- The MLC runs predictive models based on a decision-tree logic: a series of configurable nodes characterized by an "if-then-else" condition
- Decision tree is "built" offline through analysis of data sets
- It uses sensor data to compute a set of statistical parameters to identify patterns matching with user-defined classes



Adaptive self configuration (ASC)



3D orientation

Track and monitor orientation in 3D space



Detect and track device orientation with the embedded low power sensor fusion algorithm with 30 µA

Plug-and-play solution that provides 6x game rotation vector (accelerometer + gyroscope) & gyroscope-bias calibration

The rotation vector is available in quaternion format, and it can be stored in the embedded FIFO

Static accuracy(1): 0.5, 1.5, 1.5 deg

Low dynamic accuracy⁽¹⁾: 0.7, 0.5, 0.5 deg

Calibration time(2): 0.8 s

Orientation stabilization time: 0.7 s

Extra power: 30 µA @ 120 MHz



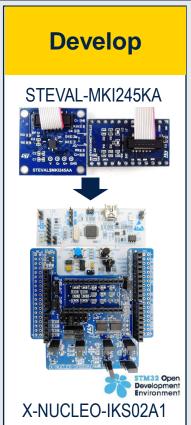
Create your application with the ISM330BX ecosystem



MEMS ecosystem for ISM330BX

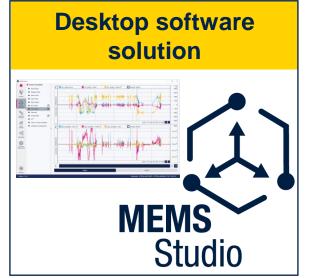
Hardware

Evaluate STEVAL-MKI245KA STEVAL-MKI109V3





Software





Ready-to-go application examples



X-CUBE-MEMS1
FP-SNS-STBOX1
FP-SNS-DATALOG2



Conclusions and takeaways



Pain points? Not anymore



A complete ecosystem to create your next solution





Getting started with <u>ISM330BX</u> adapter board



Application examples (FSM & MLC) for ISM330BX



Getting started with <u>MEMS-Studio</u> and <u>FP-SNS-</u>DATALOG2



ST MEMS & Sensors community

Our technology starts with You



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